



TSSP2011

TOHOKU UNIVERSITY SCIENCE SUMMER PROGRAM 2011

Advanced Technology and Social Science

July 25th to August 2nd 2011

About Tohoku University

Since its founding in 1907, Tohoku University has engaged in world-class education and research activities. Sendai city, where Tohoku University is located, has many cultural sites where you will have the chance to extensively experience Japanese culture.

TSSP 2011

The Tohoku University Summer Program in science and engineering has been conducted four times since 2007 with undergraduate students from all disciplines. Building on this experience and excellent results, this year we will offer the **Tohoku University Science Summer Program (TSSP)**, which is customized specially for undergraduate students in science and engineering majors. We will offer classes in advanced sciences and engineering along with the social sciences in order to examine how Advanced Technologies can be applied to the Social Sciences.

Our aims are to provide students with insight on what world society needs in the future and how they can contribute to society through research. Students will choose 7 classes out of a selection of 12, allowing them to create a course of study suited to their own interests and academic goals. The program is a 9-day summer program, which includes three components: lectures, laboratory visits, and field trips. The following topics will be covered.

- *Nano technology* • *Bio technology* • *Amorphous metal* • *Semiconductor* • *Robotics* • *Fuel Cell*
- *Artificial intelligence* • *Agent-based model on society* • *Business model and management*
- *Game theory and law* • *Game theory for economy* • *Japanese architecture*

*Above topics are subject to change.

Accommodation

Off-campus accommodation will be provided five-minutes away by bus and fifteen minutes' walk from Kawauchi campus, where most activities will be held during the program. Each student will be accommodated in a furnished individual bedroom with a unit bathroom.

Application Procedures

To apply for this program, students must be nominated by their home institutions and submit all the documents through their home institutions. Prospective students need to submit the following documents.

1. Application Form for TSSP2011
2. Photo (4cm x 3cm) on the application form
3. Personal Statement (300-500 words)
4. Copy of your passport

Eligibility

Applicants must be undergraduate students in science/engineering majors enrolled in full time undergraduate degree programs at one of the following institutions. This program requires students to be fluent in English.

China

Tsinghua University
Fudan University
Zhejiang University
Tianjin University

Germany

RWTH Aachen University

Denmark

Technical University of Denmark

Sweden

Uppsala University
KTH Royal Institute of Technology

Finland

Aalto University

France

Ecole Centrale de-Lyon
Universite de Rennes 1

United state of America

University of California Berkeley
University of California Davis
University of California San Diego
University of California Riverside
University of California Los Angeles
University of California Santa Barbara

Australia

University of Sydney

Number of Seats

30 students

Location

Tohoku University, Sendai, JAPAN

Application Deadline

June 1, 2011

Program Fee

Free (incl. Tuition, accommodation and field trips)

Travel and everyday expenses should be paid individually.

Students are advised to prepare sufficient money for food and personal expenses.

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